WHAT IS CLAIMED IS:

1. A semiconductor device comprising:

a. a leadframe comprising:

i. a source pad;

ii. at least two source lead rails at a periphery of the source pad;

iii. a gate pad adjacent the source pad and electrically isolated therefrom; and

iv. gate lead rail at a periphery of the gate pad;

b. a die coupled to the source pad and the gate pad; and

c. a stiffener coupled to the leadframe and electrically isolated therefrom.

2. A semiconductor device in accordance with claim 1 wherein the stiffener comprises a copper slug.

3. A semiconductor in accordance with claim 1 wherein the stiffener is coupled to the leadframe with polyimide tape that provides the electrical isolation.

4. A semiconductor device in accordance with claim 2 wherein the stiffener comprises a copper slug.

5. A semiconductor device in accordance with claim 4 comprising at least three source lead rails.

6. A method of making a semiconductor device, the method comprising:

providing a leadframe comprising:

a. a source pad;

b. at least two source lead rails at a periphery of the source pad;

c. a gate pad adjacent the source pad and electrically isolated therefrom; and

d. a gate lead rail at a periphery of the gate pad;

flipping a bumped die including a plurality of solder bumps onto the source and gate pads; and

reflowing the solder bumps.

7. A method in accordance with claim 6 further comprising:

performing a laser cut;

testing the semiconductor device; and

placing the semiconductor onto tape on a reel.

8. A method in accordance with claim 6 wherein the testing comprises isolating the gate pad and strip testing prior to performing the laser cut.

9. A method in accordance with claim 6 further comprising performing an underfill application and a cure after reflowing the solder bumps.

10. A method in accordance with claim 9 wherein the testing comprises isolating the gate pad and strip testing prior to performing the laser cut.

11. A semiconductor device comprising:

a. a leadframe including first and second surfaces;

b. a die coupled to the first surface; and

c. a stiffener coupled to the second surface and electrically isolated therefrom.

12. A semiconductor device in accordance with claim 11 wherein the stiffener is coupled to the leadframe with polyamide tape that provides the electrical isolation.

13. A semiconductor device in accordance with claim 11 wherein the stiffener comprises a copper slug.

14. A method of making a semiconductor device, the method comprising:

providing a leadframe including a first surface and a second surface;

coupling a die to the first surface with solder; and

reflowing the solder.